

ABSTRACT

A multi-stage jack-up structure and a die-bonding apparatus are provided. In the process of separation of the die from the base film, the terminal jack-up assembly and the first jack-up assembly are driven by the jacking unit to pass through the first jack-up avoidance hole in the first direction, after the terminal jack-up assembly and the first jack-up assembly move the first distance synchronously in the first direction, the first jack-up assembly is stopped by the first limiting portion and the first spring unit is in a compressed state. Then the terminal jack-up assembly driven by the jacking unit keeps moving in the first direction to pass through the first jack-up avoidance hole, while the first jack-up assembly is stopped, so that the terminal jack-up assembly moves upward with respect to the first jack-up assembly, to complete separation of the die from the base film.

Figure 4 accompanies.